

# N-Channel 30-V (D-S) MOSFET

| PRODUCT SUMMARY     |                                   |                    |  |  |
|---------------------|-----------------------------------|--------------------|--|--|
| V <sub>DS</sub> (V) | $R_{DS(on)}\left(\Omega\right)$   | I <sub>D</sub> (A) |  |  |
| 30                  | 0.0030 at V <sub>GS</sub> = 10 V  | 25                 |  |  |
|                     | 0.0040 at V <sub>GS</sub> = 4.5 V | 22                 |  |  |

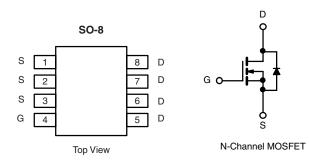
### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET<sup>®</sup> Gen II
- Ultra Low On-Resistance Using High Density TrenchFET Power MOSFET Technology





- · Synchronous Buck Low-Side
  - Notebook
  - Server
  - Workstation
- Synchronous Rectifier-POL



| <b>ABSOLUTE MAXIMUM RATINGS</b>                                 | T <sub>A</sub> = 25 °C, unle | ss otherwise r                    | noted       |              |      |
|---|------------------------------|-----------------------------------|-------------|--------------|------|
| Parameter   |                              | Symbol                            | 10 s        | Steady State | Unit |
| Drain-Source Voltage  |                              | V <sub>DS</sub>                   | 30          |              | V    |
| Gate-Source Voltage   |                              | V <sub>GS</sub>                   | ± 20        |              | V    |
| O 11 D 1 O 1 (T 150 00)   | T <sub>A</sub> = 25 °C       | I_                                | 25          | 17           |      |
| Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup> | T <sub>A</sub> = 70 °C       | l <sub>D</sub>                    | 20          | 13           |      |
| Pulsed Drain Current (10 µs Pulse Width)                        |                              | I <sub>DM</sub>                   | 70          |              | Α    |
| Continuous Source Current (Diode Conduction) <sup>a</sup>       |                              | I <sub>S</sub>                    | 2.9         | 1.3          |      |
| Avalanche Current   |                              | I <sub>AS</sub>                   | 50          |              |      |
|   | T <sub>A</sub> = 25 °C       | P <sub>D</sub>                    | 3.5         | 1.6          | W    |
| Maximum Power Dissipation <sup>a</sup>                          | T <sub>A</sub> = 70 °C       | ' D                               | 2.2         | 1            | VV   |
| Operating Junction and Storage Temperature Range                |                              | T <sub>J</sub> , T <sub>stg</sub> | - 55 to 150 |              | °C   |

| THERMAL RESISTANCE RATINGS               |              |                   |         |      |      |
|--|--------------|-------------------|---------|------|------|
| Parameter                                | Symbol       | Typical           | Maximum | Unit |      |
| Manianum lumation to Amelionata          | t ≤ 10 s     | R <sub>thJA</sub> | 29      | 35   |      |
| Maximum Junction-to-Ambient <sup>a</sup> | Steady State | ' 'thJA           | 67      | 80   | °C/W |
| Maximum Junction-to-Foot (Drain)         | Steady State | $R_{thJF}$        | 13      | 16   |      |

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

服务热线:400-655-8788

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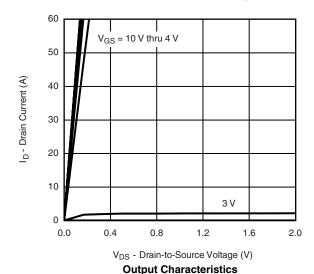
| Parameter                                     | Symbol              | Test Conditions   | Min.   | Тур.  | Max.  | Unit |
|---|---------------------|---|--------|-------|-------|------|
| Static  |                     |   |        |       |       |      |
| Gate Threshold Voltage                        | V <sub>GS(th)</sub> | $V_{DS} = V_{GS}, I_D = 250 \mu A$                                    | ıA 1.0 |       | 3.0   | V    |
| Gate-Body Leakage                             | I <sub>GSS</sub>    | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$                     |        |       | ± 100 | nA   |
| Zava Cata Valtaga Drain Current               |                     | V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V                         |        |       | 1     |      |
| Zero Gate Voltage Drain Current               | IDSS                | $V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$  |        |       | 5     | μΑ   |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>  | $V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$                       | 30     |       |       | Α    |
|   | В                   | $V_{GS} = 10 \text{ V}, I_D = 25 \text{ A}$                           |        | 0.003 |       |      |
| Drain-Source On-State Resistance <sup>a</sup> | R <sub>DS(on)</sub> | $V_{GS} = 4.5 \text{ V}, I_D = 22 \text{ A}$                          |        | 0.004 |       | Ω    |
| Forward Transconductance <sup>a</sup>         | 9 <sub>fs</sub>     | V <sub>DS</sub> = 15 V, I <sub>D</sub> = 25 A                         |        | 110   |       | S    |
| Diode Forward Voltage <sup>a</sup>            | V <sub>SD</sub>     | I <sub>S</sub> = 2.9 A, V <sub>GS</sub> = 0 V                         |        | 0.72  | 1.1   | V    |
| Dynamic <sup>b</sup>                          |                     |   |        |       |       |      |
| Input Capacitance                             | C <sub>iss</sub>    |   |        | 6500  |       |      |
| Output Capacitance                            | C <sub>oss</sub>    | $V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 20 \text{ A}$ |        | 930   |       | pF   |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>    |   |        | 610   |       |      |
| Total Gate Charge                             | $Q_g$               |   |        | 45    | 70    |      |
| Gate-Source Charge                            | $Q_{gs}$            | $V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 20 \text{ A}$ |        | 20    |       | nC   |
| Gate-Drain Charge                             | $Q_{gd}$            |   |        | 16    |       |      |
| Gate Resistance                               | $R_g$               | f = 1.0 MHz   |        | 1.1   |       | Ω    |
| Turn-On Delay Time                            | t <sub>d(on)</sub>  |   |        | 27    | 40    |      |
| Rise Time                                     | t <sub>r</sub>      | $V_{DD}$ = 15 V, $R_L$ = 15 $\Omega$                                  |        | 21    | 35    |      |
| Turn-Off Delay Time                           | t <sub>d(off)</sub> | $I_D \cong 1 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 6 \Omega$       |        | 107   | 160   | ns   |
| Fall Time                                     | t <sub>f</sub>      |   |        | 43    | 65    |      |
| Source-Drain Reverse Recovery Time            | t <sub>rr</sub>     | I <sub>F</sub> = 2.9 A, dl/dt = 100 A/μs                              |        | 45    | 70    |      |

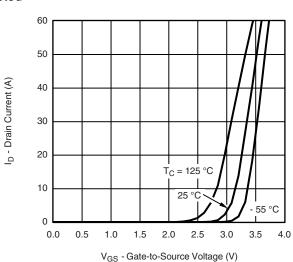
#### Notes:

- a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

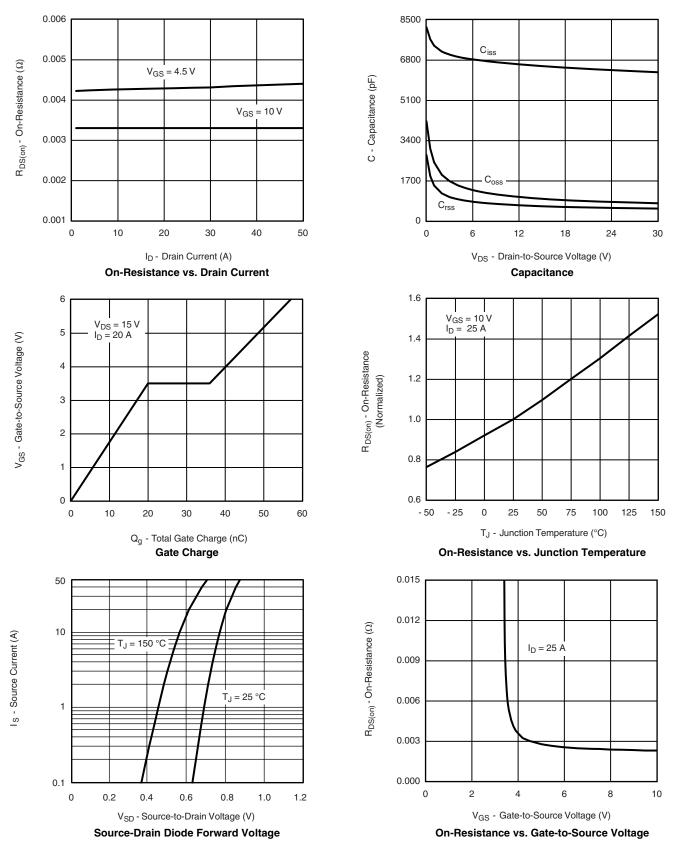




**Transfer Characteristics** 

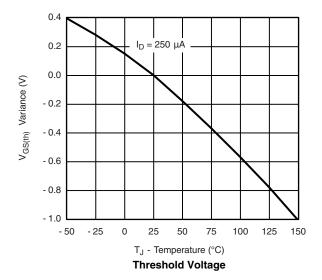


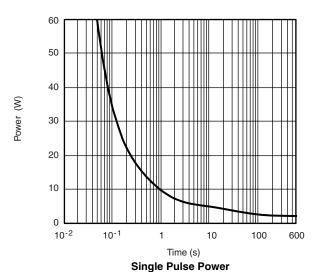
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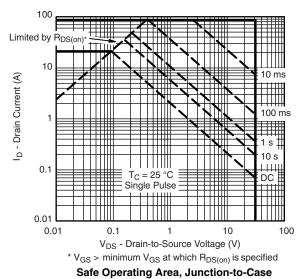




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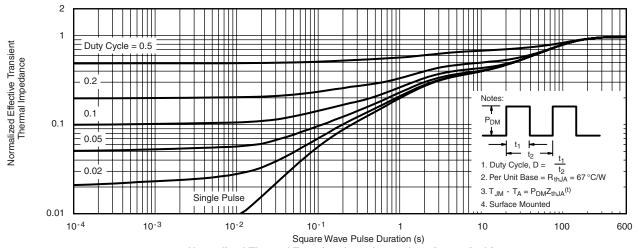




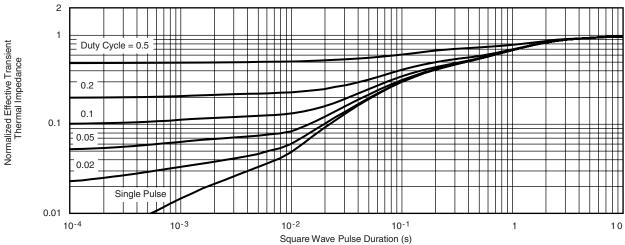




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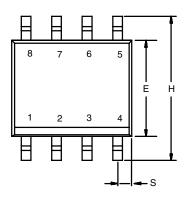
Normalized Thermal Transient Impedance, Junction-to-Ambient

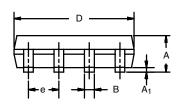


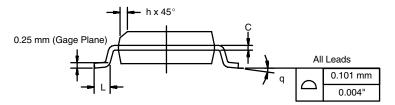
Normalized Thermal Transient Impedance, Junction-to-Foot



**SOIC (NARROW): 8-LEAD**JEDEC Part Number: MS-012





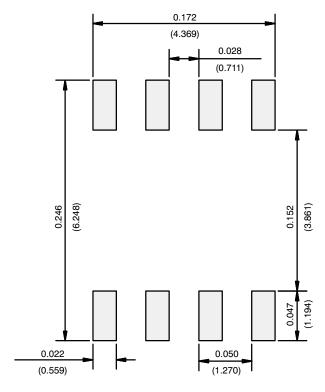


|                                | MILLIM | IETERS | INC       | INCHES |  |  |
|--------------------------------|--------|--------|-----------|--------|--|--|
| DIM                            | Min    | Max    | Min       | Max    |  |  |
| Α                              | 1.35   | 1.75   | 0.053     | 0.069  |  |  |
| A <sub>1</sub>                 | 0.10   | 0.20   | 0.004     | 0.008  |  |  |
| В                              | 0.35   | 0.51   | 0.014     | 0.020  |  |  |
| С                              | 0.19   | 0.25   | 0.0075    | 0.010  |  |  |
| D                              | 4.80   | 5.00   | 0.189     | 0.196  |  |  |
| Е                              | 3.80   | 4.00   | 0.150     | 0.157  |  |  |
| е                              | 1.27   | BSC    | 0.050 BSC |        |  |  |
| Н                              | 5.80   | 6.20   | 0.228     | 0.244  |  |  |
| h                              | 0.25   | 0.50   | 0.010     | 0.020  |  |  |
| L                              | 0.50   | 0.93   | 0.020     | 0.037  |  |  |
| q                              | 0°     | 8°     | 0°        | 8°     |  |  |
| S                              | 0.44   | 0.64   | 0.018     | 0.026  |  |  |
| ECN: C-06527-Rev. I, 11-Sep-06 |        |        |           |        |  |  |

DWG: 5498



## **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)



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